



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B104KBCNNNL

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100 nF, 50V, ±10%, X7R, 1206

## A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>104</u> <u>K</u> <u>B</u> <u>C</u> <u>N</u> <u>N</u> <u>N</u> <u>L</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor				
2	Size	1206 (inch code)	L: 3.2 ±0	).15 mm	W:	1.6 ± 0.15 mm
3	Dielectric	X7R	8 Inr	ner electrode		Ni
4	Capacitance	100 nF	Te	rmination		Cu
(5)	Capacitance	±10 %	Pla	ating		Sn 100% (Pb Free)
	tolerance		9 Pr	oduct		Normal
6	Rated Voltage	50 V	10 Sp	ecial		Reserved for future use
7	Thickness	0.85 ± 0.15 mm	① Pa	ckaging		Cardboard Type,13"reel(15,000ea)

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition			
Capacitance	Within specified tolerance	1tlb±10% 1.0±0.2Vrms			
Tan δ (DF)	0.025 max.				
Insulation	More than 500Mohm⋅ <i>μ</i> Γ	Rated Voltage 60~120 sec.			
Resistance					
Appearance	No abnormal exterior appearance	Visual inspection			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	X7R				
Characteristics	(From -55℃ to 125℃, Capacitance change should be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)			
		with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120 ℃ for 10~30sec.)			
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				

	Performance		Test condition		
Vibration Test	Capacitance change: within :	±5%	Amplitude : 1.5mm		
	Tan δ, IR : initial spec.		From 10Hz to 55Hz (return : 1min.)		
			2hours × 3 direction (x, y, z)		
Moisture	Capacitance change: within :	±12.5%	With rated voltage		
Resistance	Tan δ: 0.05 max		40±2℃, 90~95%RH, 500+12/-0 hours		
	IR : More than $25 \mathrm{M}\Omega \cdot \mu\mathrm{F}$				
High Temperature	Capacitance change: within :	±12.5%	With 200% of the rated voltage		
Resistance	Tan δ: 0.05 max		Max. operating temperature		
	IR : More than 50⋒Ω <i>·μ</i> F				
			1000+48/-0 hours		
Temperature	Capacitance change: within :	±7.5%	1 cycle condition		
Cycling	Tan δ, IR : initial spec.		Min. operating temperature → 25 ℃		
			→ Max. operating temperature → 25°C		
			5 cycles test		

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.